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Form PTO-1595

(Rev. 03/01)

OMB No. 0651-0027 (exp. 5/31/2002)



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U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

102502570

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Sang Kyun Park

Additional name(s) of conveying party(ies) attached?

☐

Yes

☒

No

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: May 15, 2003

2. Name and address of receiving party(ies)

Name: Hynix Semiconductor Inc.

Internal Address: _____

Street Address:

San 136-1, Ami-Ri
Bubal-Uep, Ichon-ShiCity: Kyungki-DoCountry: Republic of Korea Zip: _____Additional name(s) &
address(es) attached:☐

Yes

☒

No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the new application is: May 15, 2003

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached?

☐

Yes

☒

No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Michael R. Hull
MARSHALL, GERSTEIN & BORUN LLP

Internal Address: Atty. Dkt.: 29936/39484

Street Address:

233 S. Wacker Drive, Suite 6300
Sears TowerCity:
Chicago

State: IL Zip: 60606-6357

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41)

\$ 40.00

☒

Enclosed

☐

Authorized to be charged to deposit account

☐

Authorized to be charged to credit card

(Form 2038 enclosed)

8. Deposit account number:

13-2855

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Saeid Mirsafian - 52,035

Name of Person Signing

Signature

July 11, 2003

Date

Total number of pages including cover sheet, attachments, and documents: 3

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10/617473
07/11/03

07/18/2003 EDDOPEP 00000145 10617473

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PATENT
REEL: 014273 FRAME: 0671

A S S I G N M E N T

Serial No:

Filed:

Title: Plate for forming metal wires and method of forming metal wires using the same

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign(s) to Hynix Semiconductor Inc., of San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Republic of Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other U.S. applications which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States which may be obtained on any of said applications, and in any reissue or extension thereof.

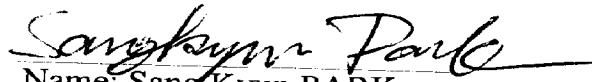
The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee. The undersigned also hereby authorizes the attorneys of Marshall, Gerstein & Borun to insert the filing date and serial number of this application in the blanks above when they become known.

The undersigned warrant(s) themselves (himself/herself) to be the owners (owner) of the interest herein assigned and to have the right to make this assignment and further warrant(s) that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree(s), upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree(s) upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent in the United States and to vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

SIGNED:

Date: May 15, 2003


Name: Sang Kyun PARK